	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	464	partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:19			
2	BRS	L2	157	partial$4 with (bond$4 or join$4) with wafer same (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:04			
3	BRS	L3	119	partial$4 with (bond$4 or join$4) with wafer with (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:05			
4	BRS	L4	69	partial$4 with (bond$4 or join$4) with wafer with (dic$4 or cut$5 or separat$4 or singulat$4) and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06			
5	BRS	L5	38	partial$4 with (bond$4 or join$4) with wafer with (dic$4 or cut$5 or separat$4 or singulat$4) and chip and align$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
6	BRS	L6	22	partial$4 with (bond$4 or join$4) with wafer with (dic$4 or cut$5 or separat$4 or singulat$4) and chip and align$5 and (cmp or polish$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:07			
7	BRS	L8	90	partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4) and rough$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			
8	BRS	L10	203	("438"/$).ccls. and partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			
9	BRS	L11	37	("438"/$).ccls. and partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4) and rough$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
10	BRS	L9	26	partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4) and rough$5 and chip and align$5 and (cmp or polish$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:11			
11	BRS	L12	7	("438"/$).ccls. and partial$4 with (bond$4 or join$4) with wafer and (dic$4 or cut$5 or separat$4 or singulat$4) and rough$5 and chip and align$5 and (cmp or polish$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:17			
12	BRS	L14	142	partial$4 with (bond$4 or join$4) near wafer and (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:19			
13	BRS	L15	51	partial$4 with (bond$4 or join$4) near wafer same (dic$4 or cut$5 or separat$4 or singulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:20			